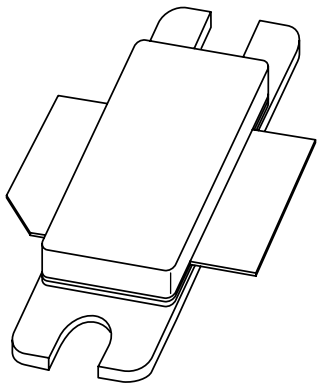


DATA SHEET



BLF2047L UHF power LDMOS transistor

Product specification
Supersedes data of 1999 Apr 01

1999 Dec 06

UHF power LDMOS transistor

BLF2047L

FEATURES

- High power gain
- Easy power control
- Excellent ruggedness
- Source on underside eliminates DC isolators, reducing common mode inductance
- Designed for broadband operation (1.8 to 2 GHz)
- Internal input and output matching for high gain and efficiency.

APPLICATIONS

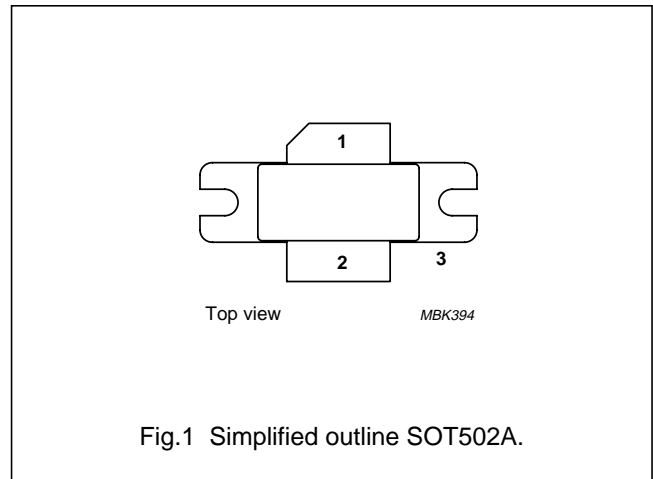
- Common source class-AB operation for PCN and PCS applications in the 1800 to 2000 MHz frequency range.

DESCRIPTION

Silicon N-channel enhancement mode lateral D-MOS transistors encapsulated in a 2-lead SOT502A flange package with a ceramic cap. The common source is connected to the mounting flange.

PINNING

PIN	DESCRIPTION
1	drain
2	gate
3	source, connected to flange



QUICK REFERENCE DATA

RF performance at $T_h = 25\text{ }^\circ\text{C}$ in a common source test circuit.

MODE OF OPERATION	f (MHz)	V_{DS} (V)	P_L (W)	G_p (dB)	η_D (%)	d_{im} (dBc)
Two-tone, class-AB	$f_1 = 2000; f_2 = 2000.1$	26	65 (PEP)	>10.5	>30	≤ -25

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V_{DS}	drain-source voltage	-	65	V
V_{GS}	gate-source voltage	-	± 15	V
I_D	DC drain current	-	9	A
T_{stg}	storage temperature	-65	+150	$^\circ\text{C}$
T_j	junction temperature	-	200	$^\circ\text{C}$

CAUTION

This product is supplied in anti-static packing to prevent damage caused by electrostatic discharge during transport and handling. For further information, refer to Philips specs.: SNW-EQ-608, SNW-FQ-302A and SNW-FQ-302B.

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THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-h}$	thermal resistance from junction to heatsink	$T_h = 25\text{ °C}$, $P_{tot} = 152\text{ W}$, note 1	1.15	K/W

Note

1. Determined under specified RF operating conditions.

CHARACTERISTICS

$T_j = 25\text{ °C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(BR)DSS}$	drain-source breakdown voltage	$V_{GS} = 0$; $I_D = 1.4\text{ mA}$	65	–	–	V
V_{GSth}	gate-source threshold voltage	$V_{DS} = 10\text{ V}$; $I_D = 140\text{ mA}$	1.5	–	3.5	V
I_{DSS}	drain-source leakage current	$V_{GS} = 0$; $V_{DS} = 26\text{ V}$	–	–	10	μA
I_{DSX}	on-state drain current	$V_{GS} = V_{GS\ th} + 9\text{ V}$; $V_{DS} = 10\text{ V}$	18	–	–	A
I_{GSS}	gate leakage current	$V_{GS} = \pm 15\text{ V}$; $V_{DS} = 0$	–	–	250	nA
g_{fs}	forward transconductance	$V_{DS} = 10\text{ V}$; $I_D = 5\text{ A}$	–	4	–	S
R_{DSon}	drain-source on-state resistance	$V_{GS} = V_{GS\ th} + 9\text{ V}$; $I_D = 5\text{ A}$	–	0.17	–	Ω
C_{rSS}	feedback capacitance	$V_{GS} = 0$; $V_{DS} = 26\text{ V}$; $f = 1\text{ MHz}$	–	3.4	–	pF

APPLICATION INFORMATION

RF performance in a common source class-AB circuit. $T_h = 25\text{ °C}$; $R_{th\ j-h} = 1.15\text{ K/W}$, unless otherwise specified.

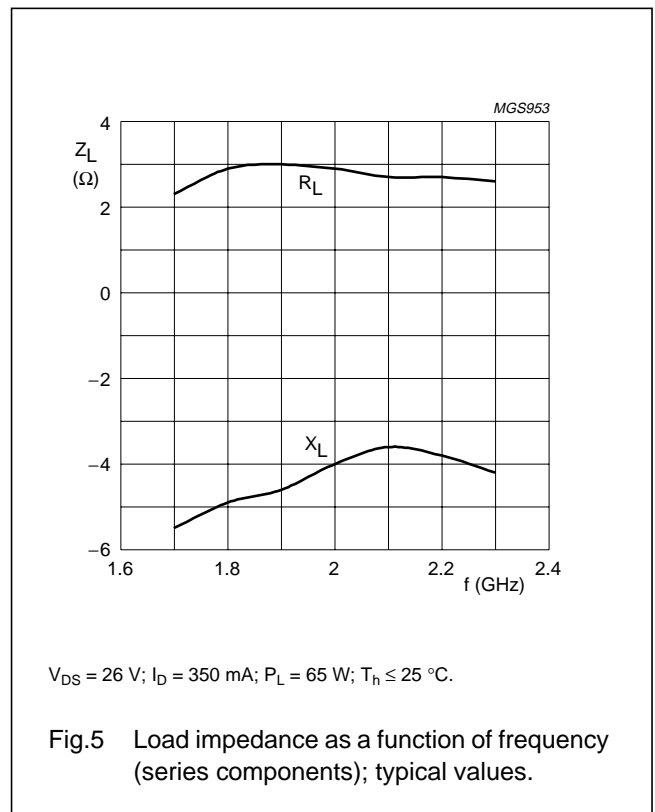
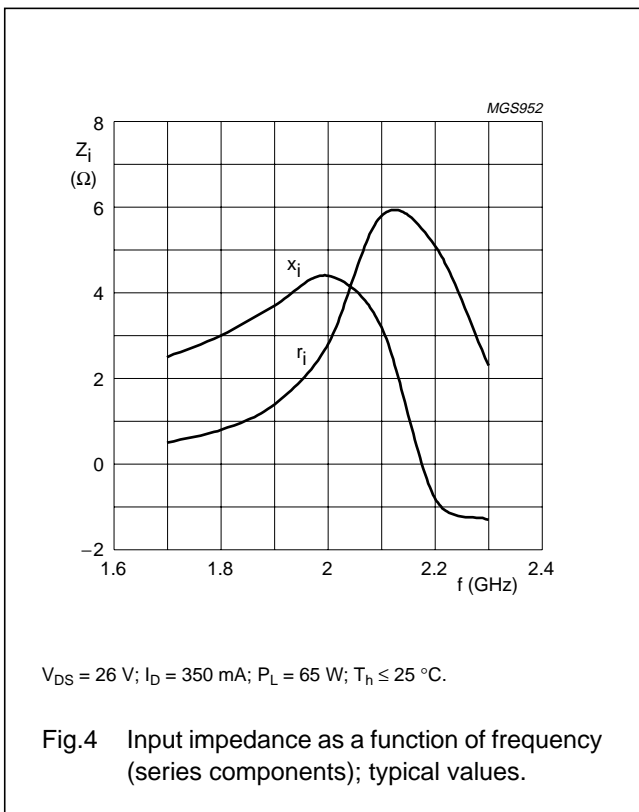
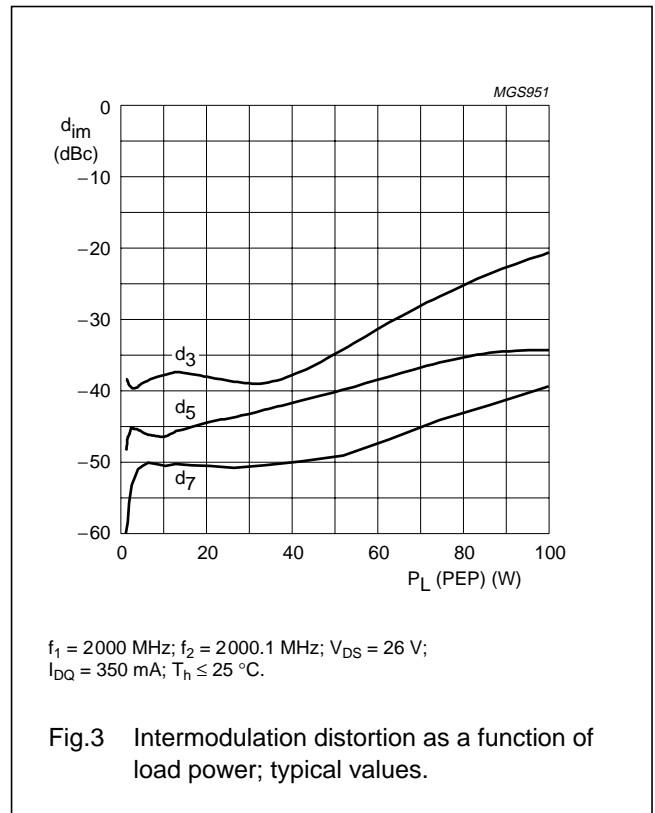
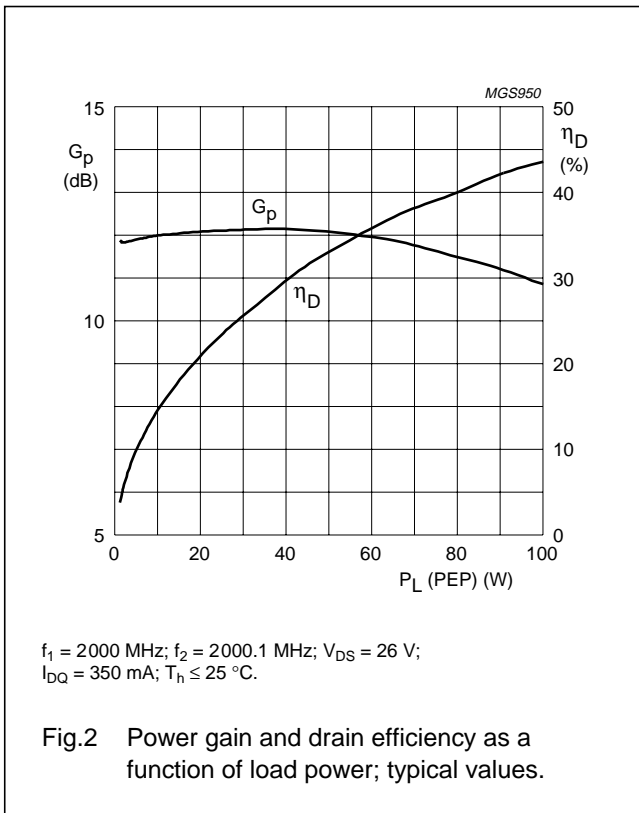
MODE OF OPERATION	f (MHz)	V_{DS} (V)	I_{DQ} (mA)	P_L (W)	G_p (dB)	η_D (%)	d_{im} (dBc)
Two-tone, class-AB	$f_1 = 2000$; $f_2 = 2000.1$	26	350	65 (PEP)	>10.5	>30	≤ -25

Ruggedness in class-AB operation

The BLF2047L is capable of withstanding a load mismatch corresponding to $VSWR = 10 : 1$ through all phases under the following conditions: $V_{DS} = 26\text{ V}$; $I_{DQ} = 350\text{ mA}$; $P_L = 65\text{ W}$; $f = 2000\text{ MHz}$.

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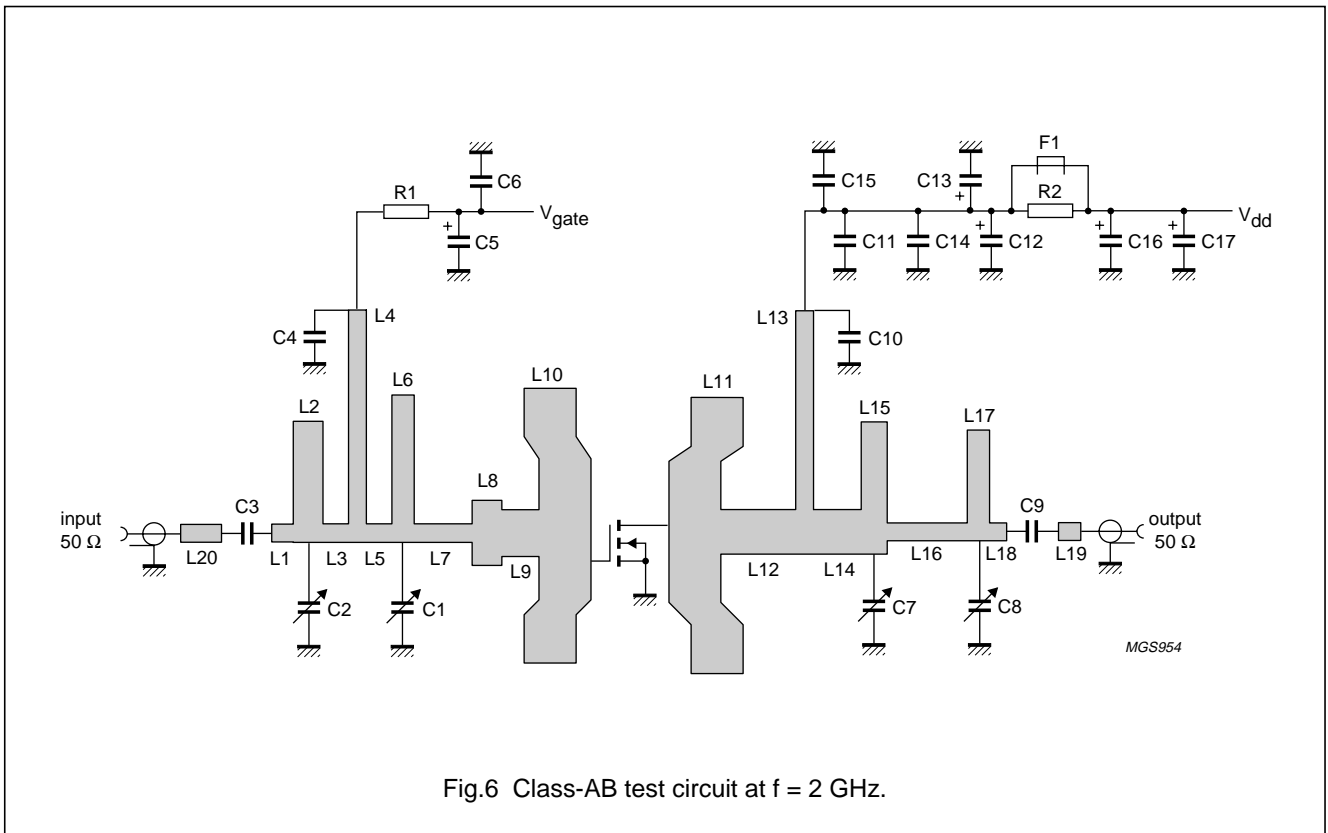


Fig.6 Class-AB test circuit at f = 2 GHz.

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List of components (see Figs. 6 and 7)

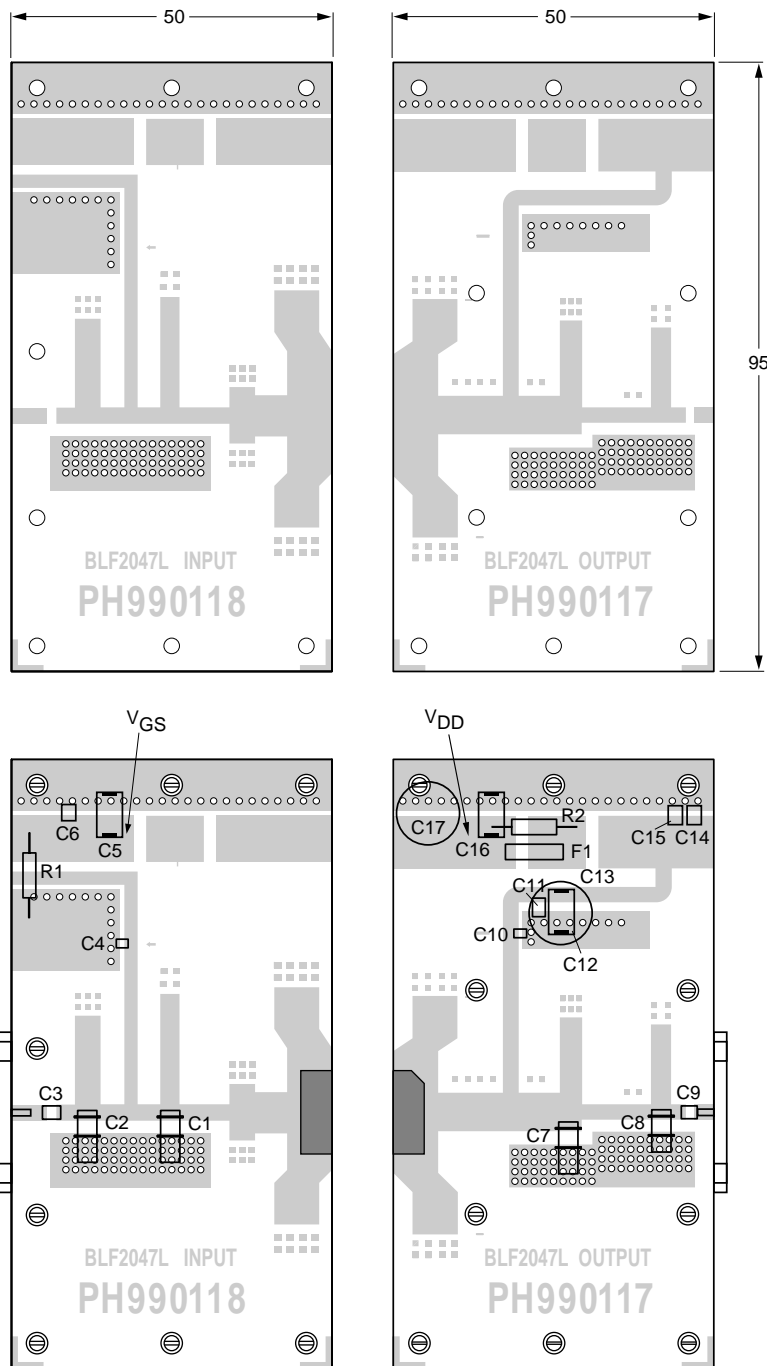
COMPONENT	DESCRIPTION	VALUE	DIMENSIONS	CATALOGUE NO.
C1, C2, C7 and C8	Tekelec variable capacitor; type 37271	0.6 to 4.5 pF		
C3, C9	multilayer ceramic chip capacitor; note 1	12 pF		
C4, C10	multilayer ceramic chip capacitor; note 2	12 pF		
C5, C12 and C16	electrolytic capacitor	4.5 μ F; 50 V		
C6, C11 and C15	multilayer ceramic chip capacitor; note 1	1 nF		
C13 and C17	electrolytic capacitor	100 μ F; 63 V		2222 037 58101
C14	multilayer ceramic chip capacitor	100 nF		2222 581 16641
F1	Ferroxcube chip-bead 8DS3/3/8/9-4S2			4330 030 36301
L1	stripline; note 3	50 Ω	2.9 \times 2.4 mm	
L2		10.8 Ω	4 \times 16.3 mm	
L3		50 Ω	3.7 \times 2.4 mm	
L4		6 Ω	2 \times 30.8 mm	
L5		50 Ω	3.6 \times 2.4 mm	
L6		9 Ω	3 \times 19.9 mm	
L7		50 Ω	7.8 \times 2.4 mm	
L8		18.5 Ω	4 \times 8.8 mm	
L9		24.4 Ω	5 \times 6.3 mm	
L10 and L11		5.1 Ω	7 \times 37 mm	
L12		25.4 Ω	10.1 \times 6 mm	
L13		5.7 Ω	2.4 \times 32.8 mm	
L14		25.4 Ω	6.4 \times 6 mm	
L15		10 Ω	3.5 \times 17.8 mm	
L16		50 Ω	10.8 \times 2.4 mm	
L17		11.8 Ω	3 \times 14.9 mm	
L18		50 Ω	2.3 \times 2.4 mm	
L19		50 Ω	3 \times 2.4 mm	
L20		50 Ω	5.5 \times 2.4 mm	
R1 and R2		metal film resistor	10 Ω , 0.6 W	

Notes

1. American Technical Ceramics type 100B or capacitor of same quality.
2. American Technical Ceramics type 100A or capacitor of same quality.
3. The striplines are on a double copper-clad printed-circuit board with Teflon dielectric ($\epsilon_r = 2.2$); thickness 0.79 mm.

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MGS955

Dimensions in mm.

The components are situated on one side of the copper-clad printed-circuit board with Teflon dielectric ($\epsilon_r = 2.2$), thickness 0.79 mm. The other side is unetched and serves as a ground plane.

Fig.7 Component layout for 2 GHz class-AB test circuit.

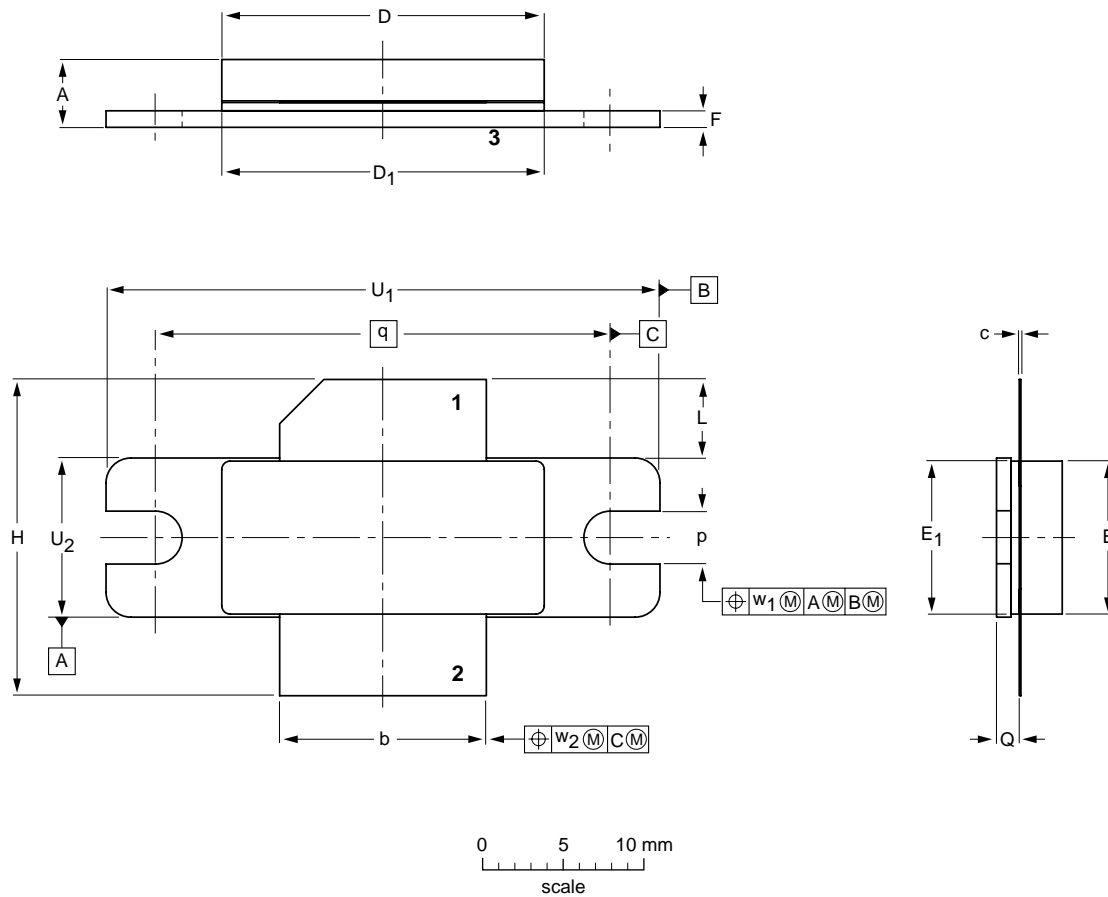
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PACKAGE OUTLINE

Flanged LDMOST package; 2 mounting holes; 2 leads

SOT502A



DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

UNIT	A	b	c	D	D ₁	E	E ₁	F	H	L	p	Q	q	U ₁	U ₂	w ₁	w ₂
mm	4.72 3.99	12.83 12.57	0.15 0.08	20.02 19.61	19.96 19.66	9.50 9.30	9.53 9.25	1.14 0.89	19.94 18.92	5.33 4.32	3.38 3.12	1.70 1.45	27.94	34.16 33.91	9.91 9.65	0.25	0.51
inches	0.186 0.157	0.505 0.495	0.006 0.003	0.788 0.772	0.786 0.774	0.374 0.366	0.375 0.364	0.045 0.035	0.785 0.745	0.210 0.170	0.133 0.123	0.067 0.057	1.100	1.345 1.335	0.390 0.380	0.01	0.02

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT502A						99-06-07 99-10-13

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DEFINITIONS

Data Sheet Status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

LIFE SUPPORT APPLICATIONS

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NOTES

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NOTES

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